

ABSTRACT OF THE DISCLOSURE

In a lead frame, a die-pad is delimited for a semiconductor element to be mounted thereon, a plurality of leads are arranged along the periphery of an area to be ultimately separated as a semiconductor device for the die-pad, and furthermore, a conductor portion for power/ground terminal is formed around the die-pad in the area between the die-pad and the leads corresponding to the die-pad. The die-pad, the leads, and the conductor portion for power/ground terminal are supported by an adhesive tape. The conductor portion for power/ground terminal is formed in the form of a single or double rings around the corresponding die-pad, or formed to partially surround the corresponding die-pad. The conductor portion for power/ground terminal is connected to at least one lead among the plurality of leads.